

## RAA223011

### 700V AC/DC Buck Regulator with Ultra-Low Standby Power

The RAA223011 is a universal input AC/DC switching buck regulator with ultra-low standby power that features a 700V integrated MOSFET capable of delivering up to 5W output power (Table 1). It supports output voltage as low as 3.3V. For higher power, use the RAA223021 device, and for low-cost small power solutions (<2W) use the RAA223012 device (Table 2).

The RAA223011 combines constant off-time control for heavy load and Pulse Frequency Modulation (PFM) for light-load operation. Constant off-time controls switching frequency above the audible frequency of approximately 30kHz. PFM eliminates any potential audible noises while offering superior light-load efficiency and ultra-low power consumption (<10mW at no load). Efficiency is achieved up to 80%. The built-in frequency dithering further reduces the EMI noise spectrum.

The RAA223011 also features input brownout protection that prevents input circuitry from the overcurrent at low input voltage, and hiccup protections for output fault conditions such as short-circuit, overload, and open feedback.

The RAA223011 is available in a small 5 Ld TSOT23, 7 Ld SOIC, and 8 Ld SOIC packages.

**Table 1. Maximum Output Current (85°C Ambient 8Ld SOIC Package)**

V <sub>OUT</sub> (V)	120V <sub>AC</sub>	230V <sub>AC</sub>	85V <sub>AC</sub> ~ 265V <sub>AC</sub>
24	200mA	220mA	170mA
12	245mA	265mA	215mA
5	270mA	300mA	240mA
3.3	300mA	300mA	280mA

## Features

- Ultra-low standby power (<10mW)
- No audible noise
- Low quiescent current (<100μA)
- Output voltage as low as 3.3V
- Low EMI with frequency dithering
- 5 Ld TSOT23, 7 Ld SOIC, and 8 Ld SOIC package options
- Programmable PFM allows optimization of C<sub>OUT</sub> for various standby power requirements
- Protection features: Short-Circuit Protection (SCP), Overload Protection (OLP), open feedback protection, and Over-Temperature Protection (OTP).

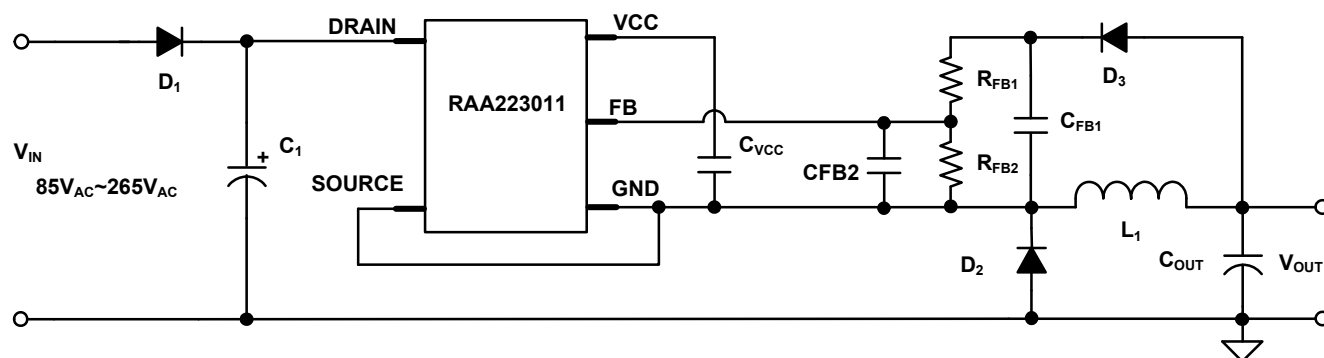
## Applications

- Home appliances
- Home automation, IoT, and sensors
- Metering and Industry control
- Bias power

## Related Literature

For a full list of related documents, visit our website:

- [RAA223011](#) device page



**Figure 1. Typical RAA223011 Buck Application Circuit**

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# 1. Overview

## 1.1 Block Diagram

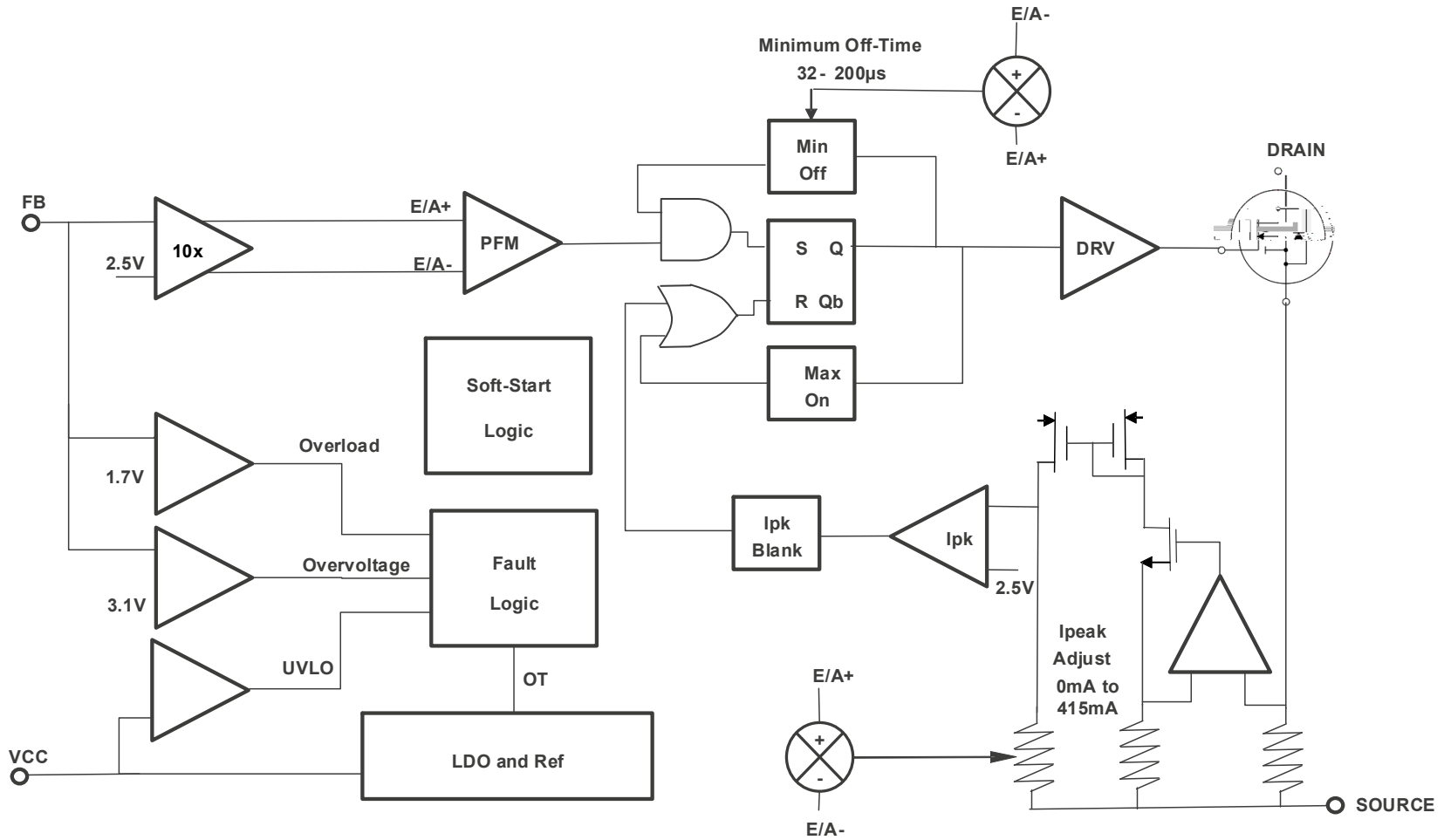
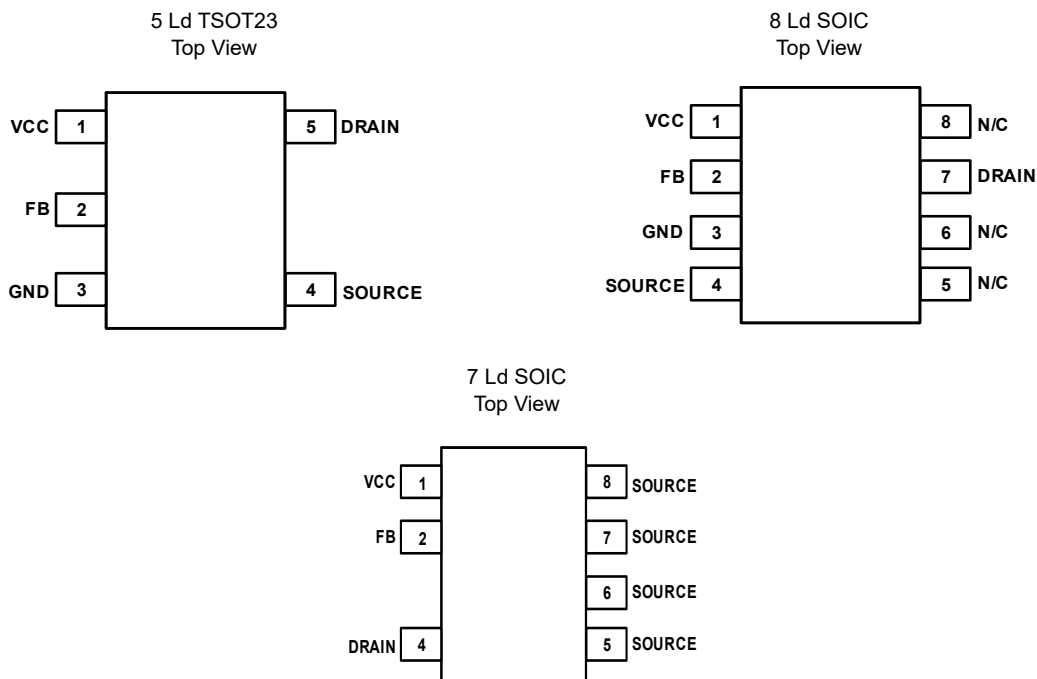


Figure 2. Block Diagram of RAA223011



## 2. Pin Information

### 2.1 Pin Configurations



### 2.2 Pin Descriptions

Pin Number			Pin Name	Description
5 Ld TSOT23	8 Ld SOIC	7 Ld SOIC		
1	1	1	VCC	IC supply voltage
2	2	2	FB	Feedback pin
3	3	-	GND	IC ground, externally connect to the SOURCE
4	4	5, 6, 7, 8	SOURCE	Source of integrated MOSFET
5	7	4	DRAIN	Drain of integrated MOSFET
-	5, 6, 8	-	N/C	Not connected

### 3. Specifications

#### 3.1 Absolute Maximum Ratings

Parameter	Minimum	Maximum	Unit
VCC	-0.3	+6.5	V
VFB	-0.3	+6.5	V
DRAIN (to SOURCE)	-0.3	700	V
Continuous Power Dissipation ( $T_A = +25^\circ\text{C}$ )		1	W
ESD Rating		Value	Unit
Human Body Model (Tested per JS-001-2017)		1.2	kV
Charged Device Model (Tested per JS-002-2014)		1	kV
Latch-Up (Tested per JESD78E; Class 2, Level A)		100	mA

**CAUTION:** Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

#### 3.2 Thermal Information

Thermal Resistance (Typical) (Notes 5, 6)	$\theta_{JA}$ ( $^\circ\text{C}/\text{W}$ )	$\theta_{JC}$ ( $^\circ\text{C}/\text{W}$ )
5 Ld TSOT23	80	60
8 Ld SOIC	89	57
7 Ld SOIC	50	28

**Notes:**

- $\theta_{JA}$  is measured on single layer 1oz evaluation PCB with 218mm<sup>2</sup> thermal copper connected to source and drain pin, in free air.
- For  $\theta_{JC}$ , the case temperature location is taken at the package top center.

Parameter	Minimum	Maximum	Unit
Maximum Junction Temperature		+150	$^\circ\text{C}$
Maximum Storage Temperature Range	-60	+150	$^\circ\text{C}$
Pb-Free Reflow Profile	See <a href="#">TB493</a>		

#### 3.3 Recommended Operating Conditions

Parameter	Minimum	Maximum	Unit
Supply Voltage, $V_{\text{DRAIN}}$		375	V
Ambient Temperature	-40	+85	$^\circ\text{C}$
Output Voltage	3.3		V

#### 3.4 Electrical Specifications

Typical operating conditions at 25 $^\circ\text{C}$ ,  $V_{\text{DRAIN}} = 100\text{V}$ ,  $V_{\text{CC}} = 5.6\text{V}$ ,  $T_J = -40$  to  $+125^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Test Conditions	Min (Note 7)	Typ	Max (Note 7)	Unit
<b>Startup and Power FET</b>						
Internal $V_{\text{CC}}$ Startup Current	$I_{\text{VCC\_START}}$	$V_{\text{CC}} = 4\text{V}$		1.6		mA
Drain Leakage Current	$I_{\text{D\_LEAK}}$	$V_{\text{CC}} = 0\text{V}$ , $V_{\text{DRAIN}} = 375\text{V}$ , $V_{\text{FB}} = 2.65\text{V}$		1		$\mu\text{A}$
$I_{\text{DRAIN}}$ Bias	$I_{\text{D\_BIAS}}$	$V_{\text{CC}} = 5.9\text{V}$ , $V_{\text{DRAIN}} = 375\text{V}$			5	$\mu\text{A}$
Power FET Breakdown Voltage	$V_{\text{DS(BR)}}$	$T_J = 25^\circ\text{C}$	700			V

Typical operating conditions at 25°C,  $V_{DRAIN} = 100V$ ,  $V_{CC} = 5.6V$ ,  $T_J = -40$  to  $+125^\circ C$ , unless otherwise specified. (Continued)

Parameter	Symbol	Test Conditions	Min (Note 7)	Typ	Max (Note 7)	Unit
Power FET On-Resistance	$r_{DS(ON)}$	$T_J = 25^\circ C$ , $V_{CC} = 5.8V$ , $I_{DS} = 200mA$		14.5	17	
		$T_J = 125^\circ C$		25	30	
<b>V<sub>CC</sub> Supply</b>						
V <sub>CC</sub> Start (Rising)	$V_{CC\_START}$		5.5	5.9	6.3	V
V <sub>CC</sub> when Internal Regulator Off	$V_{CC\_OFF}$		5.5	5.9	6.3	V
V <sub>CC</sub> (Falling) Regulator On at Startup	$V_{CC\_ON}$		5.2	5.55	5.9	V
Internal V <sub>CC</sub> On/Off Hysteresis	$V_{CC\_HYS}$		0.3	0.35	0.45	V
V <sub>CC</sub> (Falling) Regulator On after Startup	$V_{CC\_ON\_SS}$		4.25	4.55	4.8	V
V <sub>CC</sub> Undervoltage Threshold (Falling)	$V_{CC\_UVLO}$	IC stop switching	3.15	3.4	3.55	V
V <sub>CC</sub> Shunt Regulator On (Rise)	$V_{CC\_SON}$	External V <sub>CC</sub> supply, internal shunt on		6.15	6.5	V
V <sub>CC</sub> Shunt Regulator Off (Fall)	$V_{CC\_SOFF}$			6.1	6.4	V
V <sub>CC</sub> Quiescent Current	$I_{VCC\_Q}$	$V_{FB} > 2.5V$ , no switching, $V_{CC} = 5.6V$		70	103	μA
V <sub>CC</sub> Current During Switching	$I_{VCC}$	$V_{FB} < 2.5V$ , switching frequency = 30kHz, $D = 0.15$ , $V_{CC} = V_{CC\_ON} + 0.1V$		130	200	μA
V <sub>CC</sub> Discharging Current Hiccup Timing	$I_{QVCC3}$	V <sub>CC</sub> discharge current for timing of fault hiccup delay		19	30	μA
<b>Current Sense</b>						
Peak Current Limit	$I_{PK}$	$V_{FB} < 2.5V$ , $di/dt = 0.5A/\mu s$ , $V_{CC} = 5.8V$	445	520	660	mA
SCP Threshold	$I_{SC\_TH}$			750		mA
Minimum Peak Current	$I_{PKMIN}$	$di/dt = 0.5A/\mu s$ , $V_{CC} = 5.8V$		150		mA
Leading Edge Blank Time	$t_{LEB}$		217	300		ns
<b>Feedback</b>						
Feedback Voltage	$V_{FB}$		2.4	2.5	2.63	V
Transconductance	GM	$I_{PK}$ GM, $V_{CC} = 5.8V$		9		S
Feedback Undervoltage Threshold	$V_{FBUV}$	$V_{CC} = 5.7V$	1.6	1.7	1.8	V
Feedback Threshold for Increased Off-Time	$V_{FB\_TOFFMIN}$	$V_{CC} = 5.0V$	0.67	0.84	0.98	V
Feedback Overvoltage	$V_{FBOV}$		2.8	3	3.3	V
<b>Timing</b>						
Minimum Off-Time	$t_{OFF\_MIN}$	$V_{CC} = 5.0V$	24	32	37	μs
Maximum On-Time	$t_{ON\_MAX}$	$V_{CC} = 5.0V$	13	17	19	μs
Minimum Off-Time in Short-Circuit	$t_{OFFMIN\_SC}$	$V_{CC} = 5.0V$		200		μs
Hiccup Restart Delay	$t_{HICC}$	$C_{VCC} = 1\mu F$		100		ms
Startup Blanking Time, OLP Time	$t_{ST/OLP}$	$f_{SW} = 30kHz$ , $V_{FB} < 1.7V$ , $V_{CC} = 5.0V$		1024		cycle
<b>Thermal</b>						
Over-Temperature Threshold	$OTP_{TH}$			150		°C
Over-Temperature Hysteresis	$OTP_{HYS}$			30		°C

**Note:**

7. Compliance to datasheet limits is assured by one or more methods: production test, characterization, and/or design.

### 4. Typical Characterization Graphs

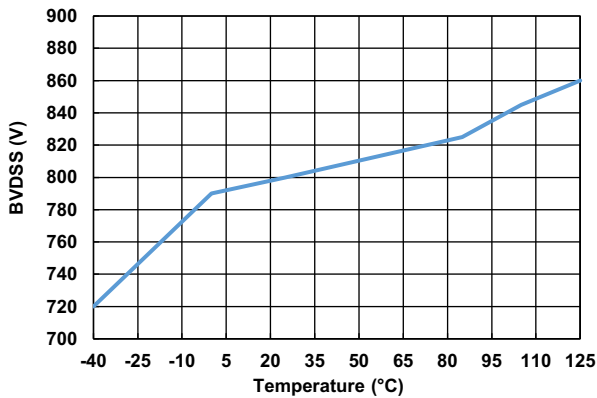


Figure 3. Breakdown Voltage vs Temperature

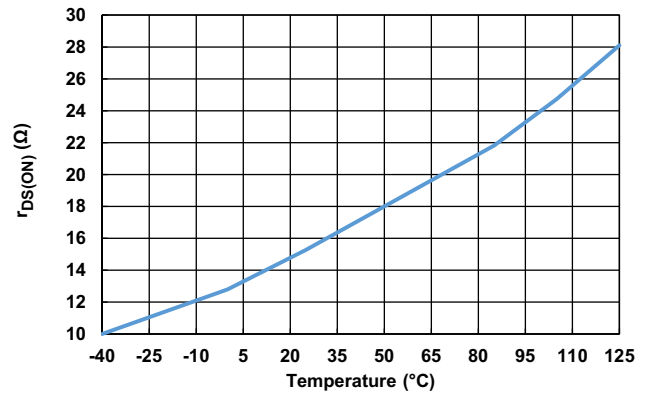


Figure 4. On-Resistance vs Temperature

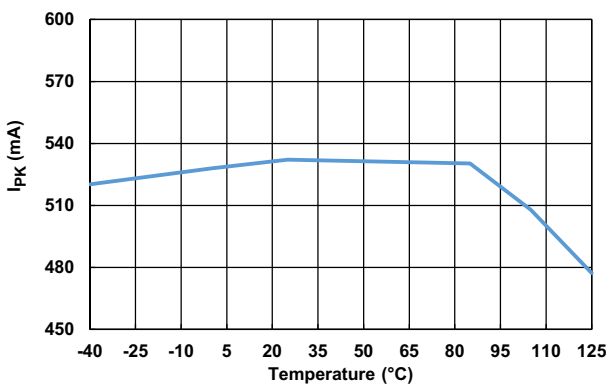


Figure 5. Peak Current Limit Over Temperature

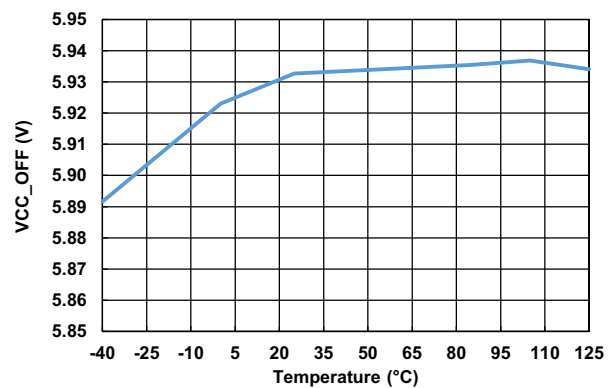


Figure 6. V<sub>CC</sub> Start/Upper Limit vs Temperature

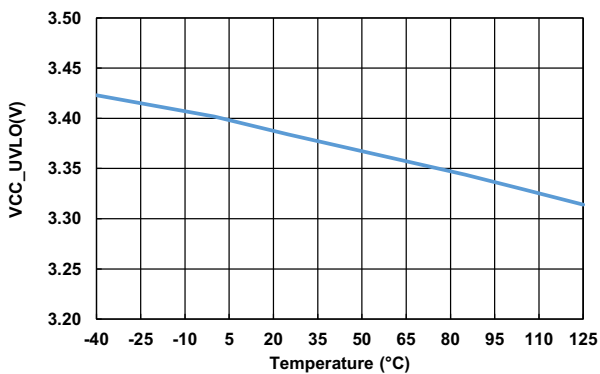


Figure 7. V<sub>CC</sub> Undervoltage Threshold vs Temperature

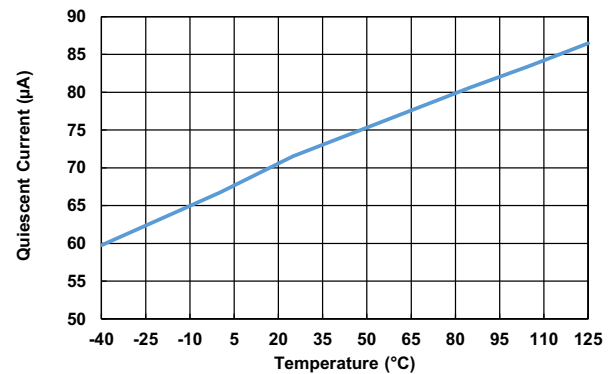


Figure 8. IC Quiescent Current vs Temperature

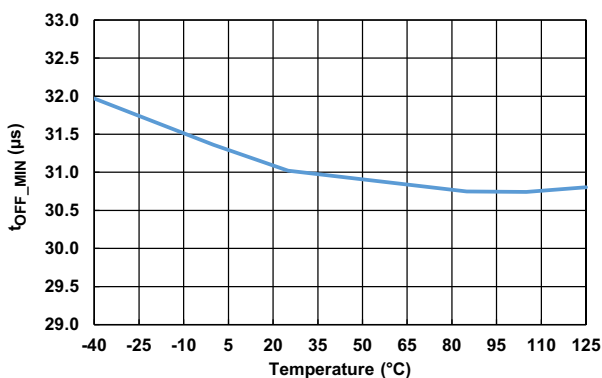


Figure 9. Minimum Off-Time vs Temperature

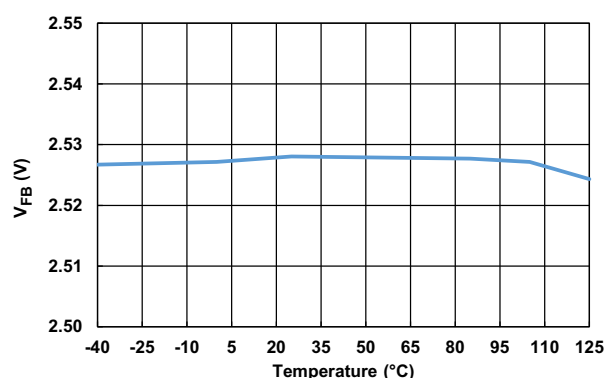


Figure 10. Feedback Voltage vs Temperature



$V_{IN} = 230V_{AC}$ ,  $V_{OUT} = 12V$ ,  $I_{OUT} = 250mA$ ,  $L = 1mH$ ,  $C_o = 470\mu F$ ,  $T_A = 25^{\circ}C$

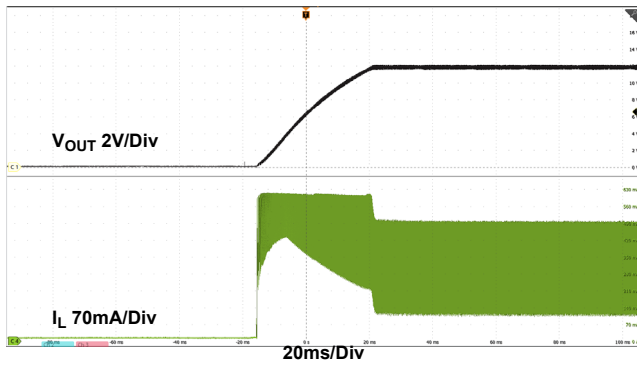


Figure 11. Startup

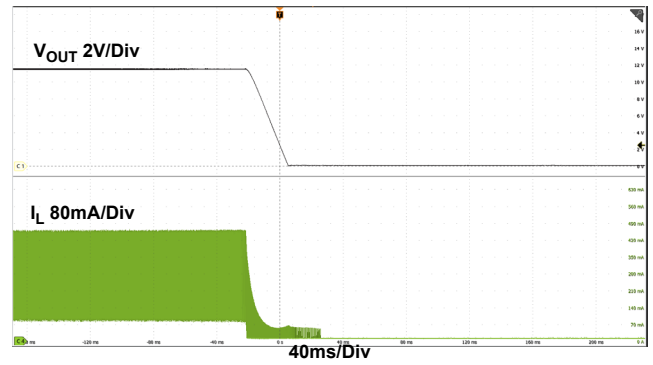


Figure 12. Shutdown

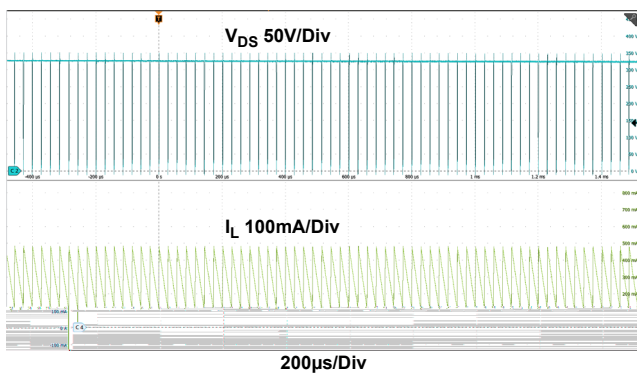


Figure 13. Full Load Operation

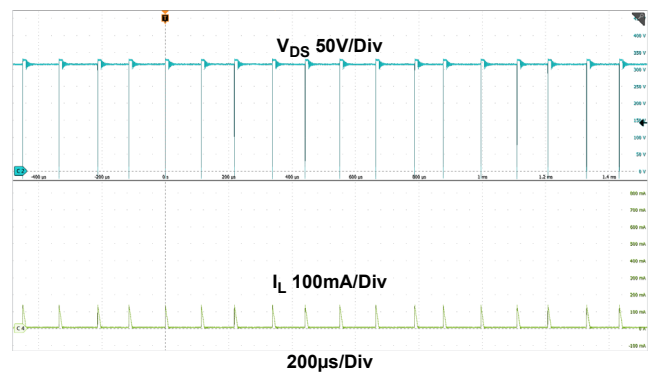


Figure 14. Light-Load Operation

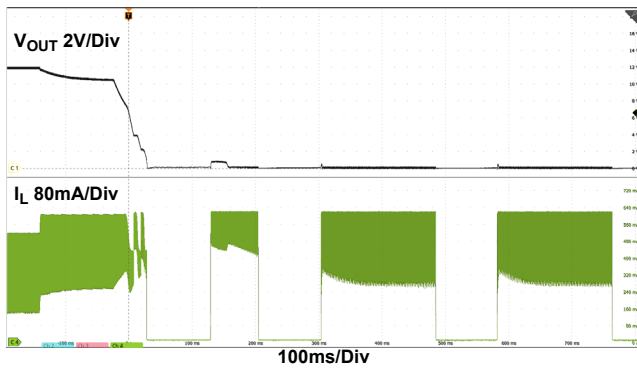


Figure 15. Overload Protection

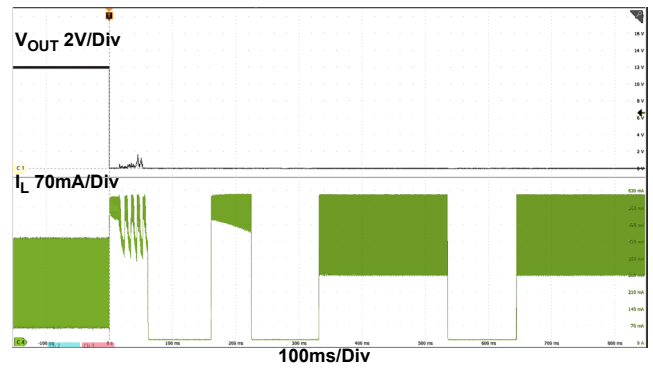


Figure 16. Short-Circuit Protection

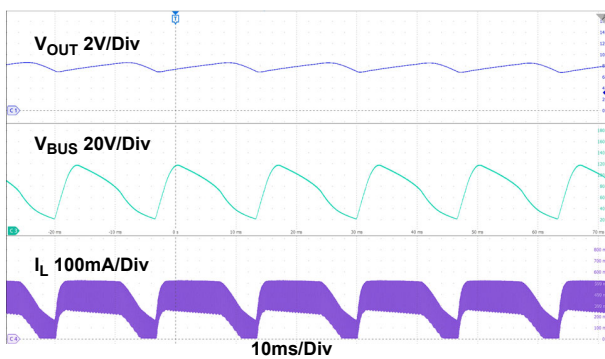


Figure 17. Input Brownout Protection

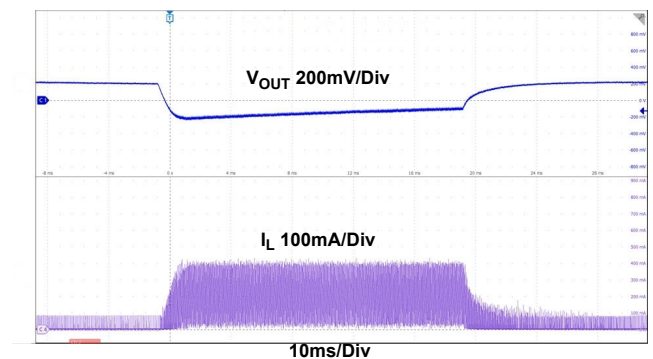


Figure 18. Load Transient (10mA to 250mA)

$V_{IN} = 230V_{AC}$ ,  $V_{OUT} = 12V$ ,  $I_{OUT} = 250mA$ ,  $L = 1mH$ ,  $C_o = 470\mu F$ ,  $T_A = 25^{\circ}C$  (Continued)

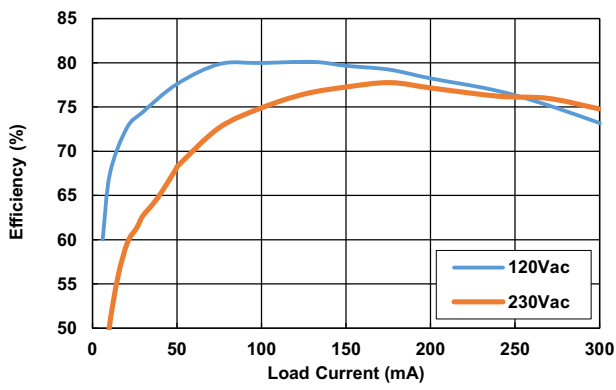


Figure 19. Efficiency ( $V_{OUT} = 12V$ )

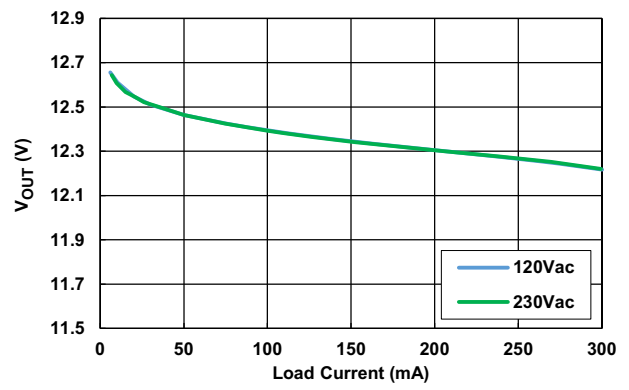


Figure 20. Load Regulation

## 5. Detailed Description

The RAA223011 adopts the high-side float switching topology as [Figure 1](#) shows. A floating VCC supplies IC operation. The output voltage is sensed on the FB pin from an RC sampling network connected to the output, and compared with the internal reference through an error amplifier that controls the peak current accordingly.

### 5.1 Constant Off-Time Mode

In heavy load, the power FET is turned on after a constant off-time. Because the on-time is comparably much smaller than the off-time, the IC operates with quasi-constant frequency. When the load current goes lower, the peak current becomes lower while still switching around 33kHz until it hits the minimum peak current limit. Because the switching frequency is always kept around 33kHz in the operation, no audible noises can be heard.

### 5.2 PFM Mode

When the load current decreases below a certain value, the peak current is kept at the minimum level, while the off-time is gradually increased to maintain the output regulation. As a result, frequency reduces too. The IC goes into Pulse Frequency Modulation (PFM) operation, as [Figure 21](#) shows, so losses are reduced because of switching frequency reduction. During this mode, while the switching frequency is reduced below 1kHz at no load, the audible noise is minimized by keeping the peak current at the minimum level. In the meantime, because of the low IC biasing current and small peak current, the standby power can be achieved below 10mW. The above operation is illustrated in [Figure 22](#) and [Figure 23](#).

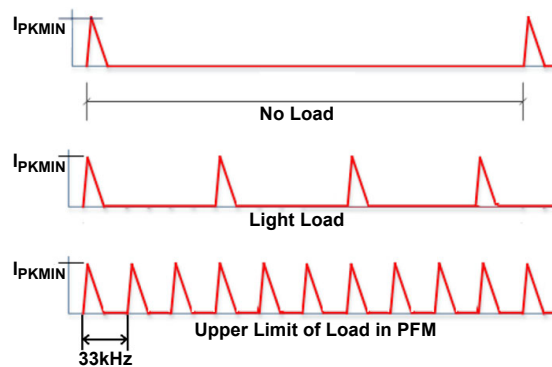


Figure 21. PFM Operation in Light Load

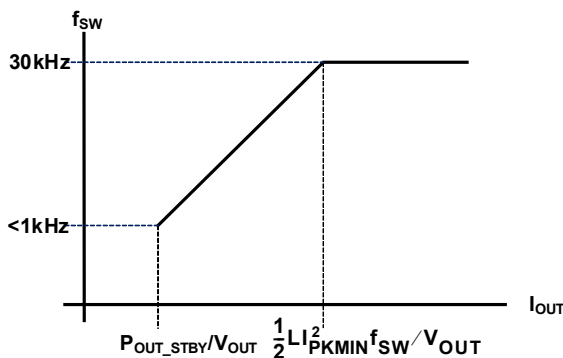


Figure 22. Switching Frequency vs  $I_{\text{OUT}}$

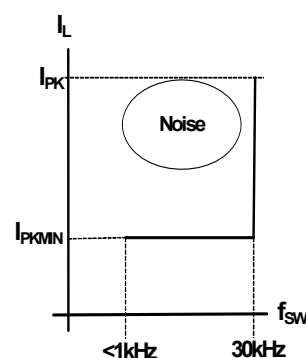


Figure 23. Peak Current vs Switching Current

### 5.3 Output Voltage Sampling

The RC sampling network samples the output voltage through a forward biased D3 when D2 is free-wheeling. When the D2 cathode goes high and D2 stops conducting current, the sampled voltage across  $C_{\text{FB1}}$  is discharged by  $R_{\text{FB1}}$  and  $R_{\text{FB2}}$ . In constant off-time operation, the FB pin voltage is slightly below the internal reference. The power FET is set on after a constant off-time. In PFM mode, when the sampled voltage on FB pin drops to internal reference, the power FET is clocked on. In this way, the light-load switching is set by the  $C_{\text{FB1}}$ ,  $R_{\text{FB1}}$ , and  $R_{\text{FB2}}$  for the corresponding load. Therefore, the required no-load standby power is achieved by choosing  $C_{\text{FB1}}$ , allowing you the flexibility to design your circuit for various standby power requirements. For detailed design guidance, see [Feedback Capacitor \( \$C\_{\text{FB1}}\$ \) Selection](#).

### 5.4 Soft Start-Up

The RAA223011 starts up with the  $V_{CC}$  capacitor charged by an internal HV current source. When the  $V_{CC}$  reaches up to 5.9V, the IC begins switching, the internal HV current source is turned off, and a start-up timer begins. When  $V_{CC}$  drops below 5.5V, the HV current source is on again, which is determined by the actual IC supply current. During the start-up, the output voltage ramps up gradually, which is controlled by a variable off-time set by the feedback voltage. After the timer expires (start-up is finished), the HV current source is on again only when  $V_{CC}$  drops to 4.5V. When  $V_{OUT}$  is established,  $V_{CC}$  can be supplied by  $V_{OUT}$  (optional) to save power consumption for high efficiency and low standby power, see [Figure 24](#).

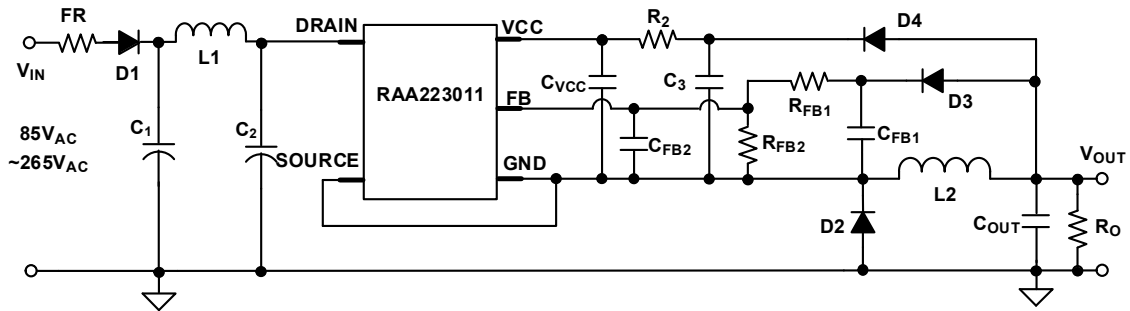


Figure 24. RAA223011 Low Standby Power Buck Regulator

[Figure 25](#) shows the start-up diagram.

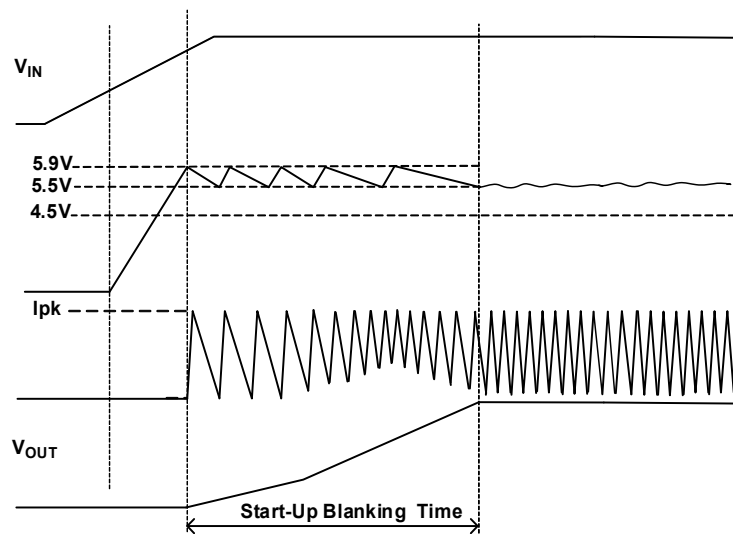


Figure 25. RAA223011 Start-Up Diagram

### 5.5 Overload Protection

With the fixed minimum off-time (when  $V_{FB} = 0.84V$ ), the maximum load current that the RAA223011 allows is limited for a given output voltage and inductor, and therefore, is the maximum output power (<5W). However, when the output voltage continues to drop during the overload, the FET power losses increase and can cause potential IC overheating. Therefore, when  $V_{FB}$  reaches 1.7V, an internal comparator is triggered and starts an Overload Protection (OLP) timer. When the timer is expired, the overload situation is identified and the IC is shut off.  $V_{CC}$  is discharged by a  $19\mu A$  internal current source to 3.4V and then charged up to 5.9V to resume switching (the interval without switching is the hiccup time). The overload protection time sequence is shown in [Figure 26](#).

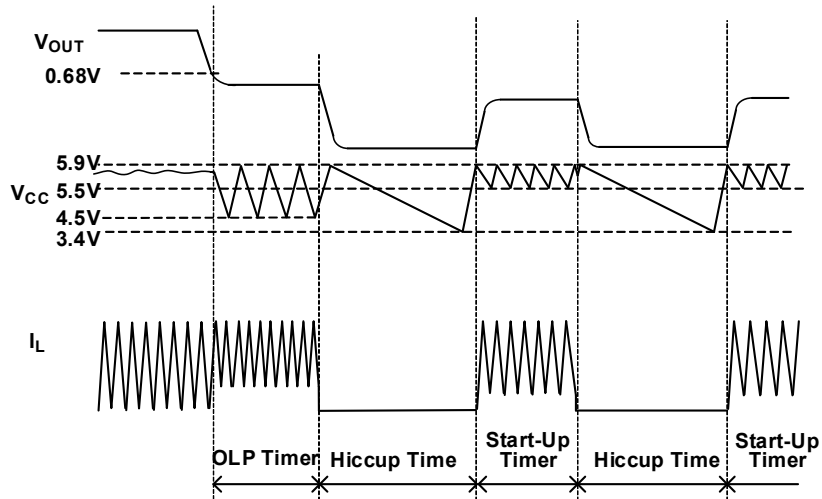


Figure 26. RAA223011 Overload Protection Diagram

### 5.6 Short-Circuit Protection

When the output is shorted,  $V_{OUT} = 0$ ,  $V_{FB}$  drops to zero because of the feedback network, introducing a delay. Before  $V_{FB}$  drops to  $V_{FB\_TOFFMIN}$ , the RAA223011 operates with  $T_{ONMAX}$  and  $T_{OFFMIN}$ , which quickly builds up a high current ( $>I_{PK}$ ) because the inductor peak current does not get reset. When the current reaches  $I_{SC\_TH}$ , a timer is started. If the inductor current reaches  $I_{SC\_TH}$  for four consecutive cycles, the RAA223011 determines that a short-circuit is present and immediately shuts off switching. The IC then quickly charges  $V_{CC}$  up to 5.9V and discharges it with a 19 $\mu$ A current source to 3.4V. When  $V_{CC}$  drops to 3.4V, a 1.6mA current source charges  $V_{CC}$  back to 5.9V where the IC resumes switching.

When the RAA223011 resumes switching, assuming  $V_{FB}$  drops to zero, the IC operates with the increased  $T_{OFFMIN\_MAX}$  so the inductor current can fully reset below the maximum peak limit. The RAA223011 operates in CCM with the inductor peak current being limited at  $I_{PK}$ , with an average current around 400mA during the short. The part remains in hiccup mode until the short is removed. When the short is removed,  $V_{OUT}$  returns to normal. This procedure is shown in [Figure 27](#).

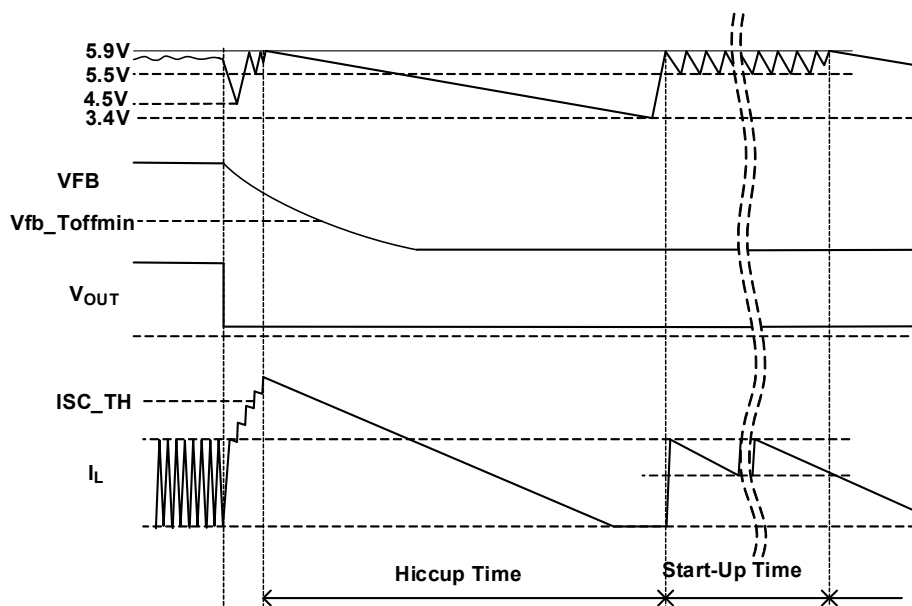


Figure 27. RAA223011 Short-Circuit Protection Diagram

## 6. Application Topologies

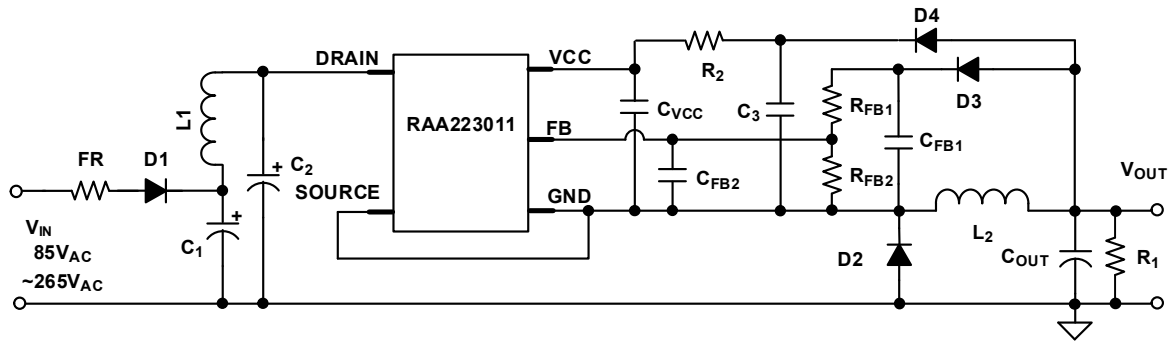


Figure 28. RAA223011 Buck with Enhanced Efficiency and Low Standby Power

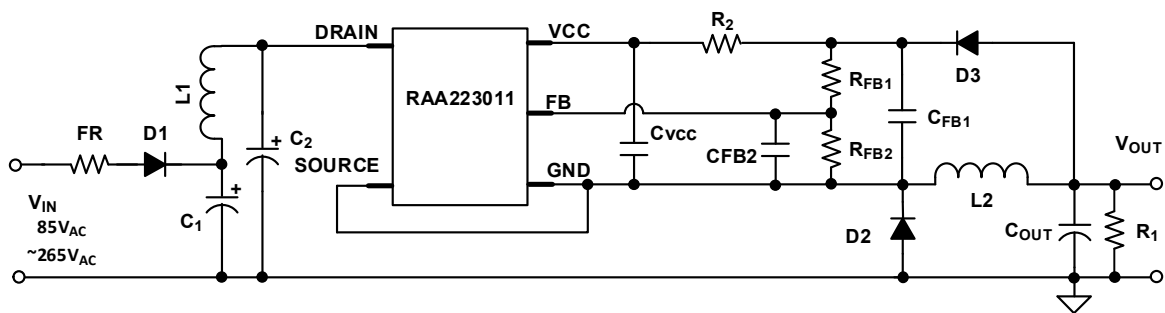


Figure 29. RAA223011 Buck with Enhanced Efficiency

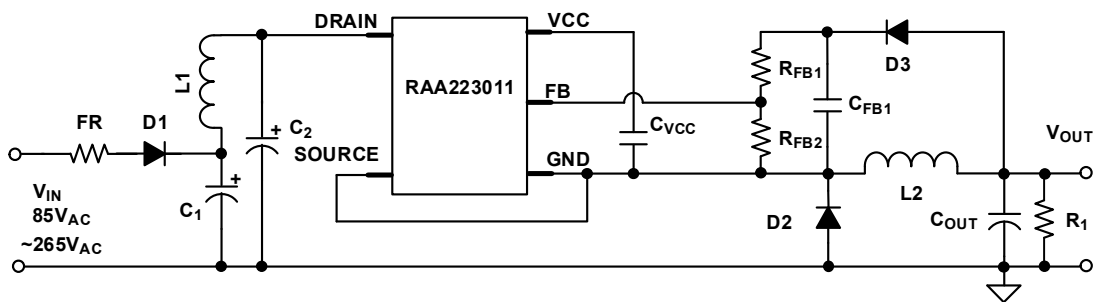


Figure 30. RAA223011 Buck with Low BOM Cost

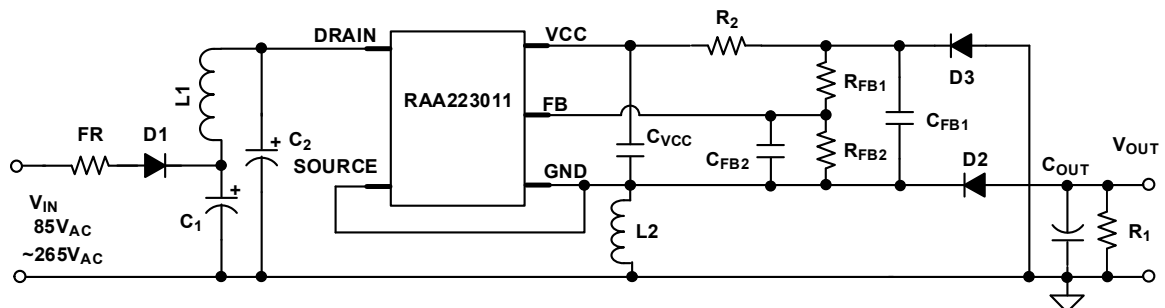


Figure 31. RAA223011 Buck/Boost

## 7. Design Guidance

### 7.1 Feedback Resistor Selection

The output voltage is set by the resistor divider of  $R_{FB1}$  and  $R_{FB2}$ . Because of the diode forward voltage mismatch between the feedback diode D3 and free-wheeling diode D2, an additional 0.4V offset is added in [Equation 1](#) to calculate the resistor values of  $R_{FB1}$  and  $R_{FB2}$ .

$$(EQ. 1) \quad \frac{R_{FB1}}{R_{FB2}} = \frac{V_{OUT} + 0.4}{V_{FB}} - 1$$

### 7.2 Output Inductor Selection

Because the buck regulator is designed with a constant off-time of  $28\mu s$  at full load, design the output inductor according to [Equation 2](#):

$$(EQ. 2) \quad L \geq \frac{V_{OUT} t_{OFF\_MIN}}{2(I_{PK\_MIN} - I_{O\_MAX})}$$

For example, if  $V_{OUT} = 12V$ , if  $I_{O\_MAX} = 300mA$ ,  $L \geq \frac{12 \times 32 \times 10^{-6}}{2 \times (0.52 - 0.3)} = 873\mu H$

L is chosen with a fixed value  $1000\mu H$ .

### 7.3 Feedback Capacitor ( $C_{FB1}$ ) Selection

The feedback capacitor  $C_{FB1}$  determines the pulse frequency at no load condition. The corresponding inductor current is shown in [Figure 32](#).

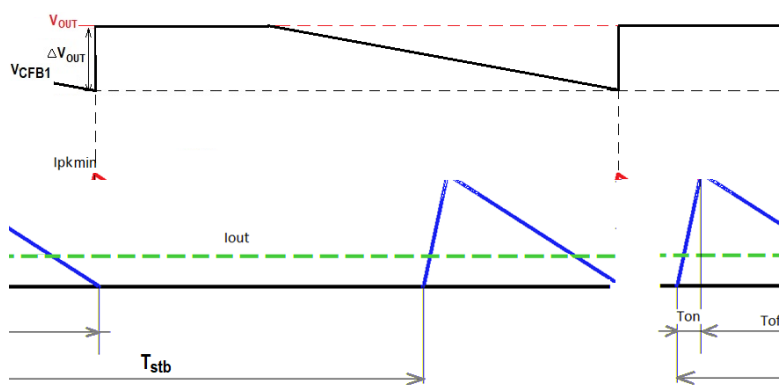


Figure 32. The Inductor Current at No Load Operation

The average output current can be written as [Equation 3](#).

$$(EQ. 3) \quad \frac{I_{PK\_MIN}(T_{ON} + T_{OFF})}{2T_{STB}} = I_{OUT\_MIN}$$

Because  $T_{ON} \ll T_{OFF}$ ,  $I_{OUT\_MIN}$  can be written as:

$$\frac{I_{PK\_MIN} T_{OFF}}{2T_{STB}} = I_{OUT\_MIN} \quad , \quad \text{where } T_{OFF} = \frac{L I_{PK\_MIN}}{V_{OUT}}$$

Therefore:

$$(EQ. 4) \quad I_{OUT\_MIN} = \frac{L(I_{PK\_MIN})^2}{2V_{OUT} T_{STB}}$$

To have the required input standby power,  $P_{IN\_STBY}$ , the power delivered to the output should satisfy [Equation 5](#):

$$(EQ. 5) \quad V_{OUT} I_{OUT\_MIN} = \eta P_{IN\_STBY}$$

where  $\eta$  is the light-load efficiency.

Replacing  $I_{OUT\_MIN}$  with [Equation 4](#) gives you [Equation 6](#).

$$(EQ. 6) \quad V_{OUT} \left( \frac{L(I_{PK\_MIN})^2}{2V_{OUT}T_{stb}} \right) = P_{IN\_STBY}\eta$$

The required time interval  $T$  is calculated using [Equation 7](#):

$$(EQ. 7) \quad T_{stb} = \frac{L(I_{PK\_MIN})^2}{2P_{IN\_STBY}\eta}$$

Because the time interval  $T_{stb}$  is primarily determined by the sampling network discharging time, it is related to  $C_{FB1}$  in [Equation 8](#):

$$(EQ. 8) \quad C_{FB1} = \frac{V_{OUT}T_{stb}}{\Delta V_{OUT}(R_{FB1} + R_{FB2})}$$

where  $V_{OUT}$  is the output voltage increase above the nominal  $V_{OUT}$  at no load.

From [Equation 8](#), it can be seen that a bigger sampling capacitor leads to a smaller  $V_{OUT}$ , but  $C_{FB1}$  can not be too big as it calls for a huge  $C_{OUT}$ . A small  $V_{OUT}$  can cause erratic logic function of the internal PFM comparator in mode transition. Therefore, choose  $V_{OUT}$  properly according to the highest  $V_{OUT}$  allowed in the applications. When  $V_{OUT}$  is picked,  $C_{FB1}$  is calculated using [Equation 8](#).

## 7.4 Output Capacitor Selection

The output capacitor does not only need to meet the requirement of output ripple voltage and load transient response, but also needs to ensure the slew rate of the output voltage is slower than the discharging rate of the sampling capacitor,  $C_{FB1}$ , in a defined step load transient, as shown in the [Figure 33](#). Therefore,  $C_{OUT}$  is first calculated according to  $V_{OUT}$  discharging by [Equation 9](#).

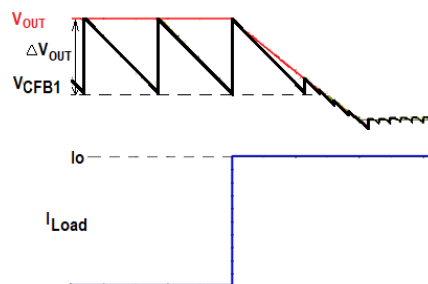


Figure 33. Output Capacitor Discharging at Step Load

$$(EQ. 9) \quad C_{OUT} \geq \frac{C_{FB1} \Delta I_{OUT} (R_{FB1} + R_{FB2})}{V_{OUT}}$$

However, the output capacitor should also be large enough to provide sufficient transient voltage suppression in response to any potential load step, because the controller most likely cannot detect the voltage change and take action promptly.



(EQ. 10)  $C_{OUT} \geq \frac{\Delta I_{OUT} T}{0.07 V_{OUT}}$

where 7% voltage drop is used in this example.

### 7.5 Dummy Resistor Selection

At no load condition, the system standby power is determined by the IC quiescent current and the feedback resistor bleeding current. If the required standby power is not low, a dummy resistor can be added in parallel with the output capacitor to keep a no-load output voltage from getting too high. Its value is calculated using [Equation 11](#).

(EQ. 11)  $R_O = \frac{V_{OUT}}{\left( \frac{P_{IN\_STBY} \eta}{V_{OUT}} - I_q - \frac{V_{FB}}{R_{FB2}} \right)}$ , where  $\eta = 0.4$

### 7.6 Power Capability

The maximum power the RAA223011 can deliver depends on the ambient temperature, output voltage, input voltage, and even PCB thermal design. In general, higher input voltage with lower ambient temperature allows a bit more power than a low input voltage at higher ambient temperature. Also, it delivers more power at higher output voltages. [Table 1](#) summarizes the maximum power the RAA223011 can deliver with ambient temperature up to 85C. This table should be used as a reference and may vary because of actual PCB thermal design.

### 7.7 PCB Layout Guidance

Proper layout is important to ensure a stable operation, good thermal behavior, EMI performance, and reliable operation for various operating environments. Pay attention to the following layout recommendations:

- Leave proper spacing between high voltage (max 400V) traces and low voltage traces (minimum 1.4mm).
- Keep a small loop from the input filter capacitor to the IC, switching inductor, output capacitor, and to the ground of the input capacitor. Also, a small loop consisting of a switching inductor, output capacitor, and freewheeling diode.
- Keep sufficient copper area on the IC drain and/or source pin (not less than 220mm<sup>2</sup> for 3-4W output power) for better thermal performance.
- Keep the switching inductor away from the input EMI inductor to avoid noise coupling, especially when an unshielded switching inductor is used.
- Place the V<sub>CC</sub> decoupling capacitor and the FB pin decoupling capacitor close to the pins. A PCB layout example is shown in [Figure 34](#).

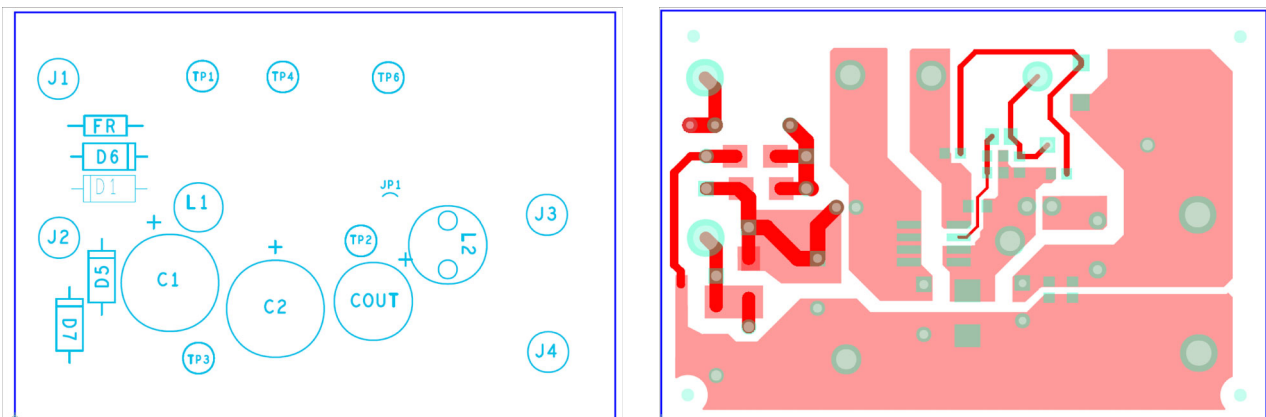


Figure 34. Example PCB Layout

## 8. EMI Performance

Conducted and Radiated EMI compliance for EN55022/CISPR22 (12V/260mA output).

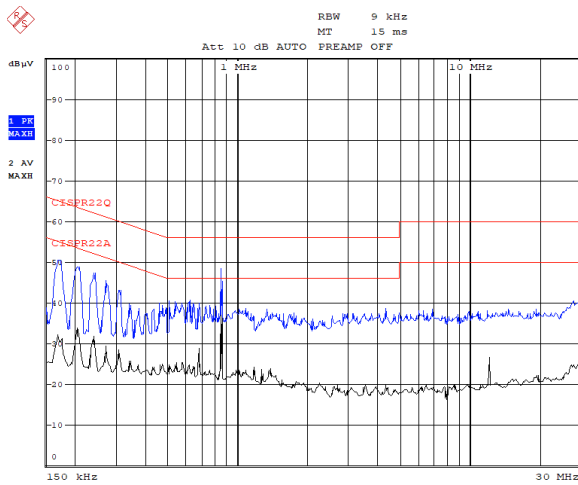


Figure 35. Line, 120V<sub>AC</sub>

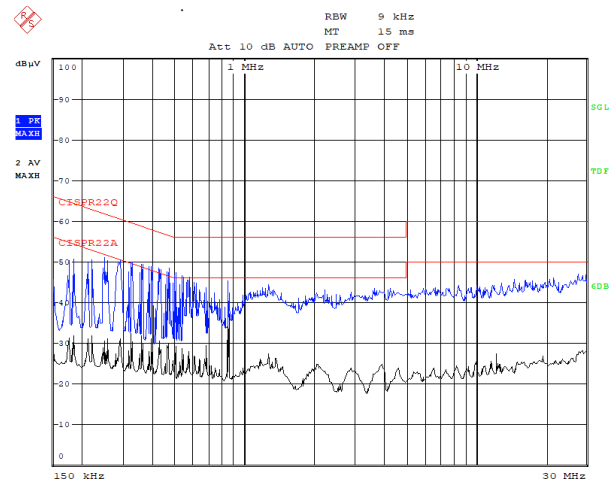


Figure 36. Line, 230V<sub>AC</sub>

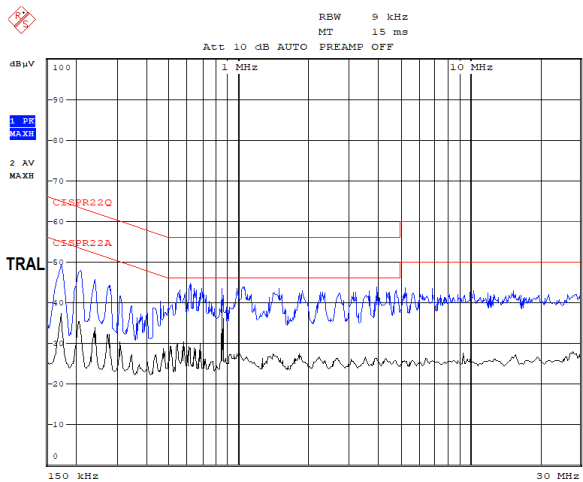


Figure 37. Neutral, 120V<sub>AC</sub>

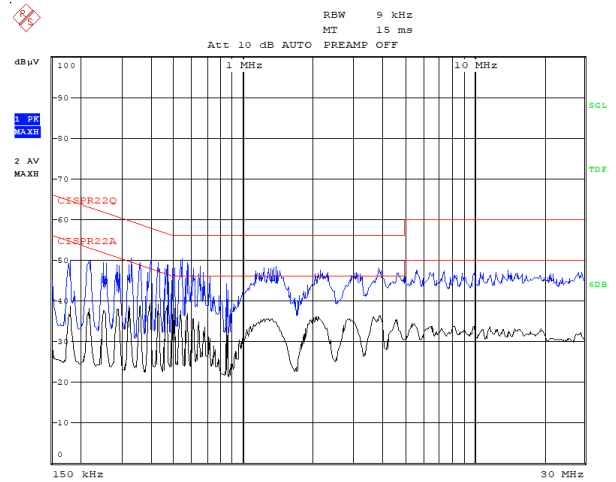


Figure 38. Neutral, 230V<sub>AC</sub>

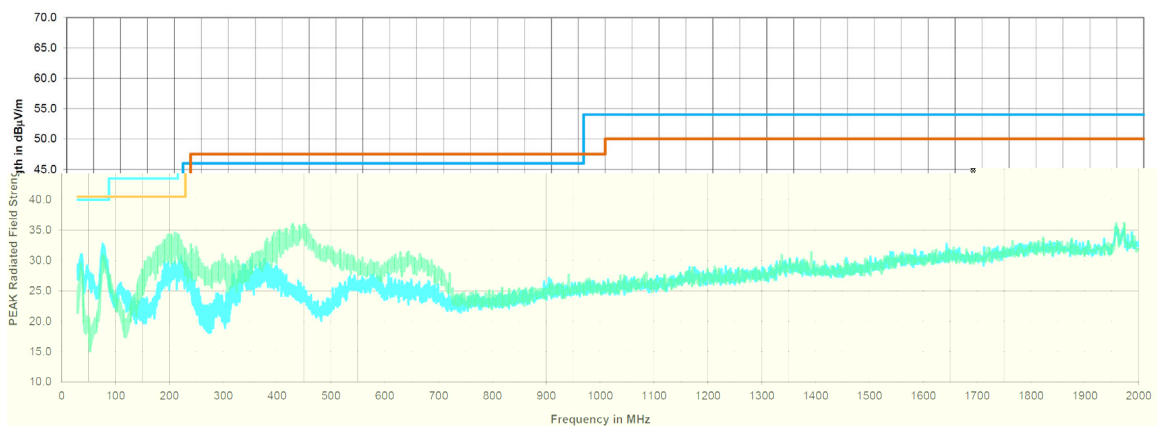


Figure 39. FCC Part15/CISPR22 Class B Radiated Emissions at 3 Meters, 120V<sub>AC</sub>, 60Hz (Peak Detector)

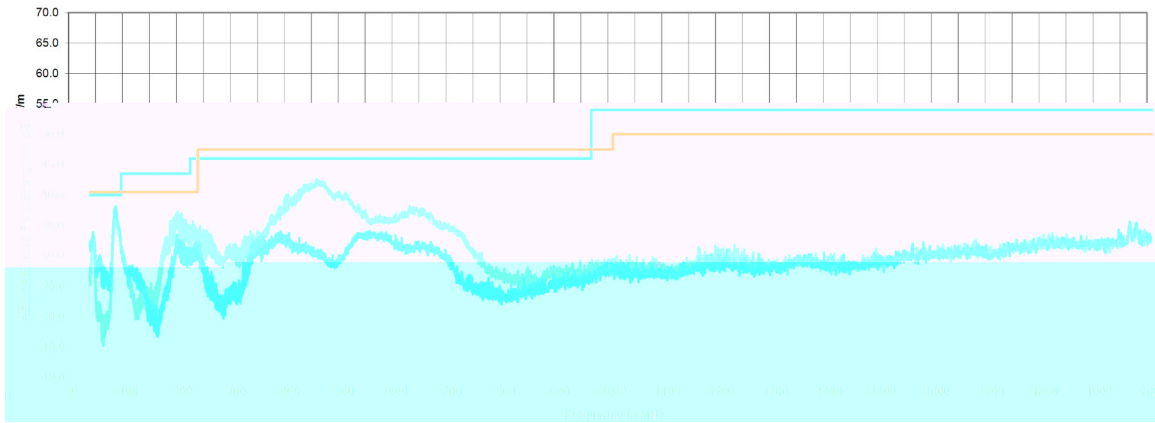


Figure 40. FCC Part15/CISPR22 Class B Radiated Emissions at 3 Meters, 230V<sub>AC</sub>, 50Hz (Peak Detector)

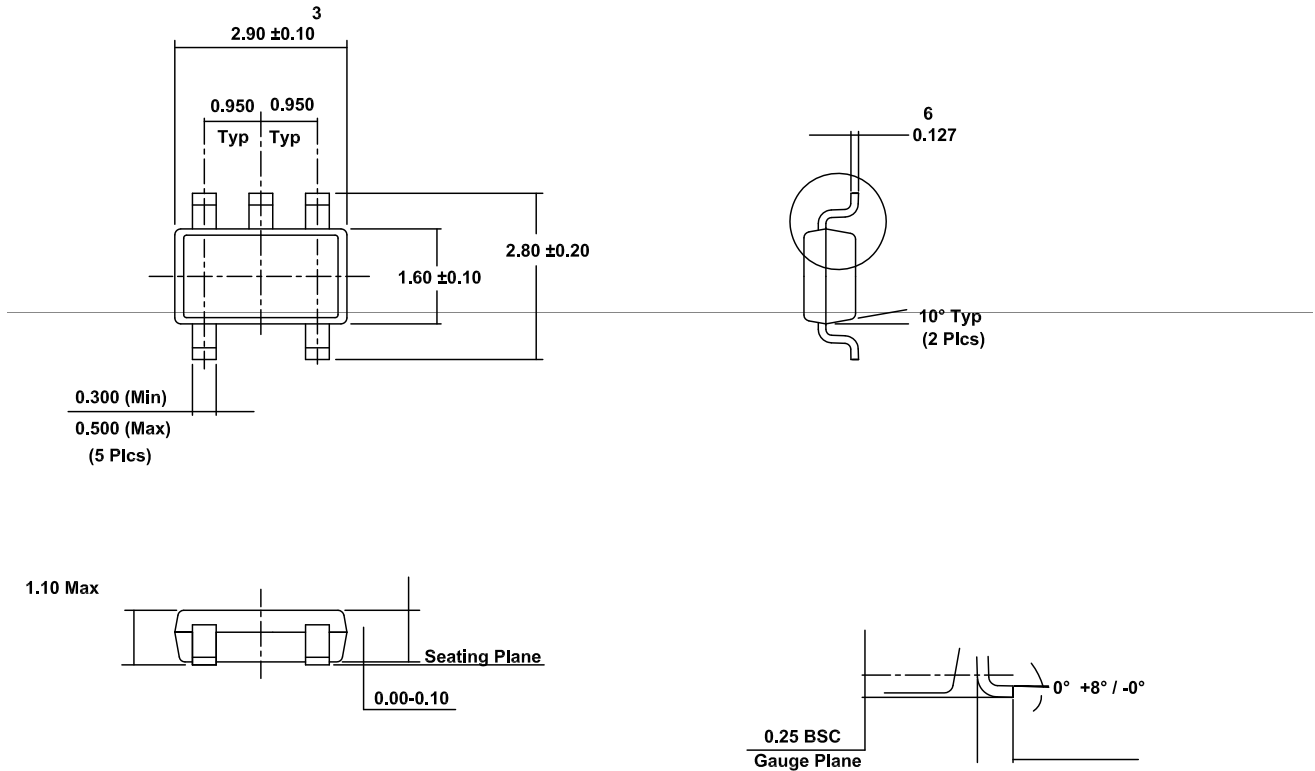
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## 9. Revision History

Rev.	Date	Description
1.2	Feb 25, 2021	Updated Figure 31.
1.1	Feb 18, 2021	Corrected Pin numbers for the 7 Ld SOIC package in the Pin Configurations section.
1.0	Dec 16, 2020	Initial release

# 10. Package Outline Drawings

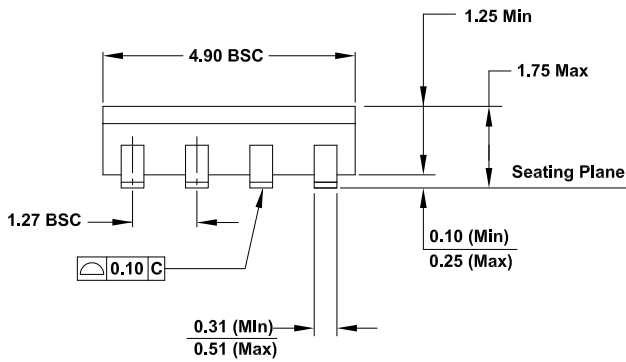
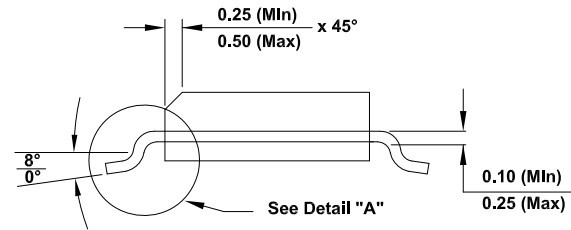
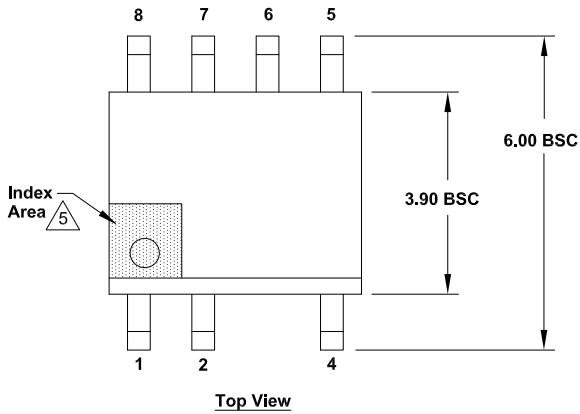
P5.064B  
 5 Lead Thin Small Outline Transistor (TSOT) Plastic Package  
 Rev 1, 1/20



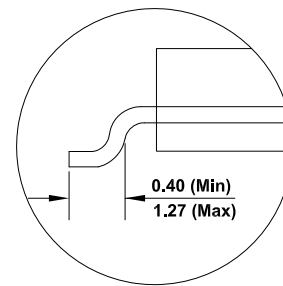
1. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
2. Die Is facing up for mold. Die Is facing down for trlm/form, that Is reverse trlm/form.
3. Dimensions are exclusive of mold flash and gate burr.
4. The footlength measuring is based on the
- 5.
6. Dimensions are exclusive of solder plating.

M7.15A  
 7 Lead Narrow Body Small Outline Plastic Package (SOIC)  
 Rev 1,12/20

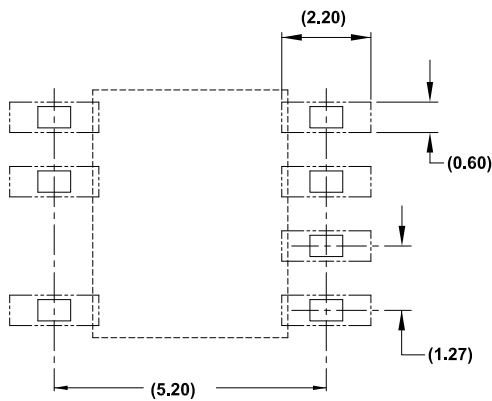
For the most recent package outline drawing, see [M7.15A](#).



**Side View "B"**



**Detail "A"**



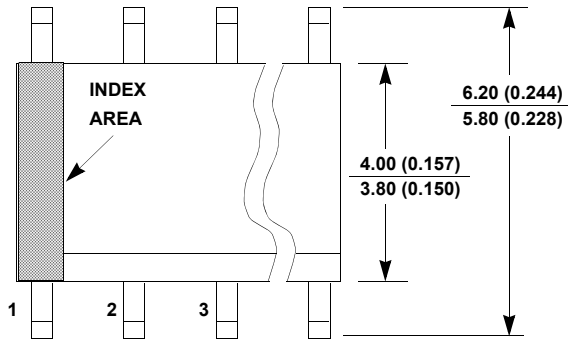
**Typical Recommended Land Pattern**

**Notes:**

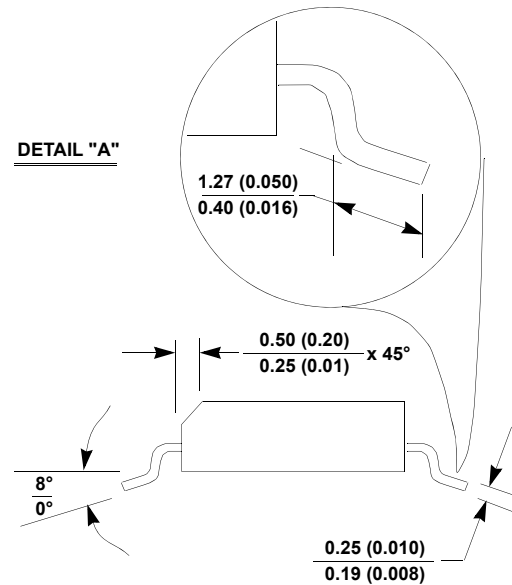
1. Dimensions are in millimeters.  
Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
3. Unless otherwise specified, tolerance: Decimal  $\pm 0.05$
4. Dimension does not include interlead flash or protrusions.  
Interlead flash or protrusions shall not exceed 0.255mm per side.
5. The pin #1 identifier may be either a mold or mark feature.
6. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.

M8.15  
 8 Lead Narrow Body Small Outline Plastic Package  
 Rev 4, 1/12

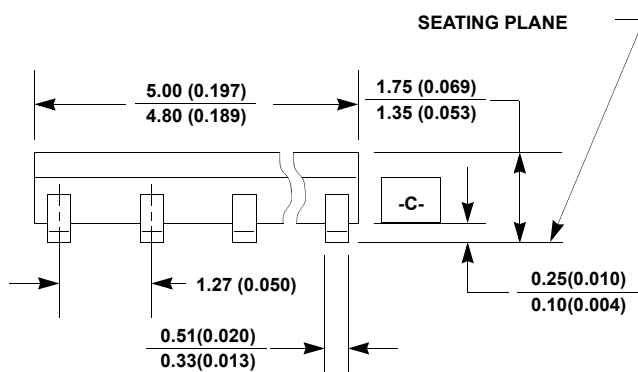
For the most recent package outline drawing, see [M8.15](#).



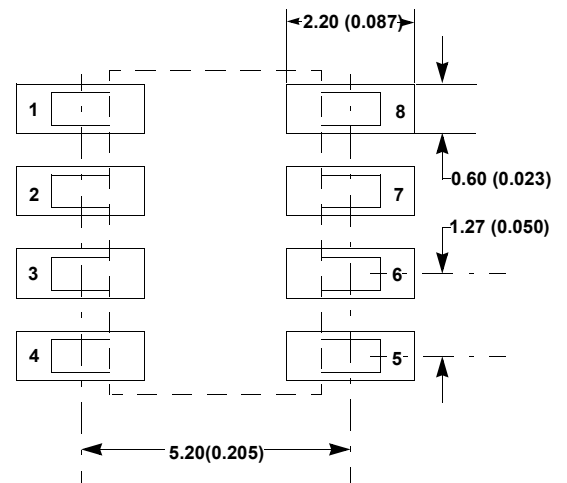
**TOP VIEW**



**SIDE VIEW "B"**



**SIDE VIEW "A"**



**TYPICAL RECOMMENDED LAND PATTERN**

**Notes:**

1. Dimensioning and tolerancing per ANSI Y14.5M-1994.
2. Package length does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
3. Package width does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
4. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
5. Terminal numbers are shown for reference only.
6. The lead width as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
7. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.
8. This outline conforms to JEDEC publication MS-012-AA ISSUE C.

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(Rev.1.0 Mar 2020)

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